

IN THE CLAIMS

Please amend the claims to read as follows:

1        1. (Twice Amended) A method of marking a chip having surfaces comprising the following  
2        steps:

3                forming internal marking indicia on a marking location upon an exterior surface of the  
4        chip for identification of the chip, and

5                forming a non-black, optically transmissive encapsulating material over at least the  
6        marking location on the one exterior surface of the chip which non-black, optically

7                transmissive material cannot be easily scraped off of the chip for prevention of replacement of  
8        the internal marking indicia by different markings.

1                3. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive  
2        encapsulating material is a protective encapsulating material adapted to provide protection  
3        from damage as the result of environmental and handling factors.

1                6. (Twice Amended) The method of claim 1 wherein the non-black, optically transmissive  
2        material comprises a material such as epoxy which prevents remarking indicia or  
3        identification marks on the chip.

1        12. (Twice Amended) A method of marking a chip having surfaces comprising:

2                forming internal marking indicia on a marking location upon an exterior surface of the  
3        chip, and

4                forming a non-black, optically transparent material colored with a particular color over  
5        at least the marking location on that exterior surface of the chip wherein the material colored  
6        with the particular color together with the marking indicia represents identification of the chip  
7        which non-black, optically transparent, colored material cannot be easily scraped off of the  
8        chip for prevention of replacement of the internal marking indicia by different markings.

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*B6  
B7  
S15  
C14  
G9*

**13. (Twice Amended) A chip comprising:**  
~~the chip having exterior surfaces,~~  
~~internal marking indicia formed on a marking location upon an exterior surface~~  
~~of the chip for identification of the chip, and~~  
~~a non-black, optically transmissive material formed over at least the marking location~~  
~~on the one exterior surface of the chip which non-black, optically transmissive material cannot~~  
~~be easily scraped off for prevention of replacement of the internal marking indicia by different~~  
~~markings.~~

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**22. (Twice Amended) An electronic integrated circuit chip comprising:**  
~~a semiconductor, integrated circuit chip having surfaces including a planar front~~  
~~surface, a planar back surface and edges of the chip between the planar surfaces with at least~~  
~~one electrical contact site on a surface,~~  
~~indicia marked upon an exterior marking portion of a surface of the chip for~~  
~~identification of the chip,~~  
~~a non-black layer covering the exterior surface of the chip at least at the exterior~~  
~~marking portion thereof, the non-black layer being composed of a colored, optically~~  
~~transmissive material which non-black, optically transmissive material cannot be easily~~  
~~scraped off of the chip for prevention of replacement of the indicia by different markings and~~  
~~for preventing remarked the indicia on the exterior marking surface of the chip, and~~  
~~the indicia being visible through the non-black layer.~~

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**25. (Twice Amended) A chip comprising:**  
~~internal marking indicia formed on a marking location upon an exterior surface of the~~  
~~chip, and~~  
~~a non-black, optically transparent material colored with a particular color formed over~~  
~~at least the marking location on that exterior surface of the chip wherein the material colored~~  
~~with the particular color together with the marking indicia represents identification of the chip~~  
~~which non-black, optically transmissive material cannot be easily scraped off of the chip for~~